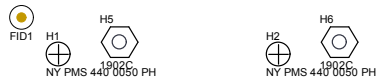


Multi-phase config	J1	J2	J3	J01	J02	J23	Assembly Variant
0 (4)	B	B	B	Y	Y	Y	001
1 (3-1)	B	B	A	Y	Y	N	002
2 (2-2)	B	A	B	Y	N	Y	003
3 (2-1-1)	B	A	A	Y	N	N	004
4 (1-1-1-1)	A	A	A	N	N	N	005
5 - 9 (4)	B	B	B	Y	Y	Y	001

J0 should be assembled in all configurations

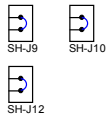


PCB Number: TIDA-00719
PCB Rev: 001

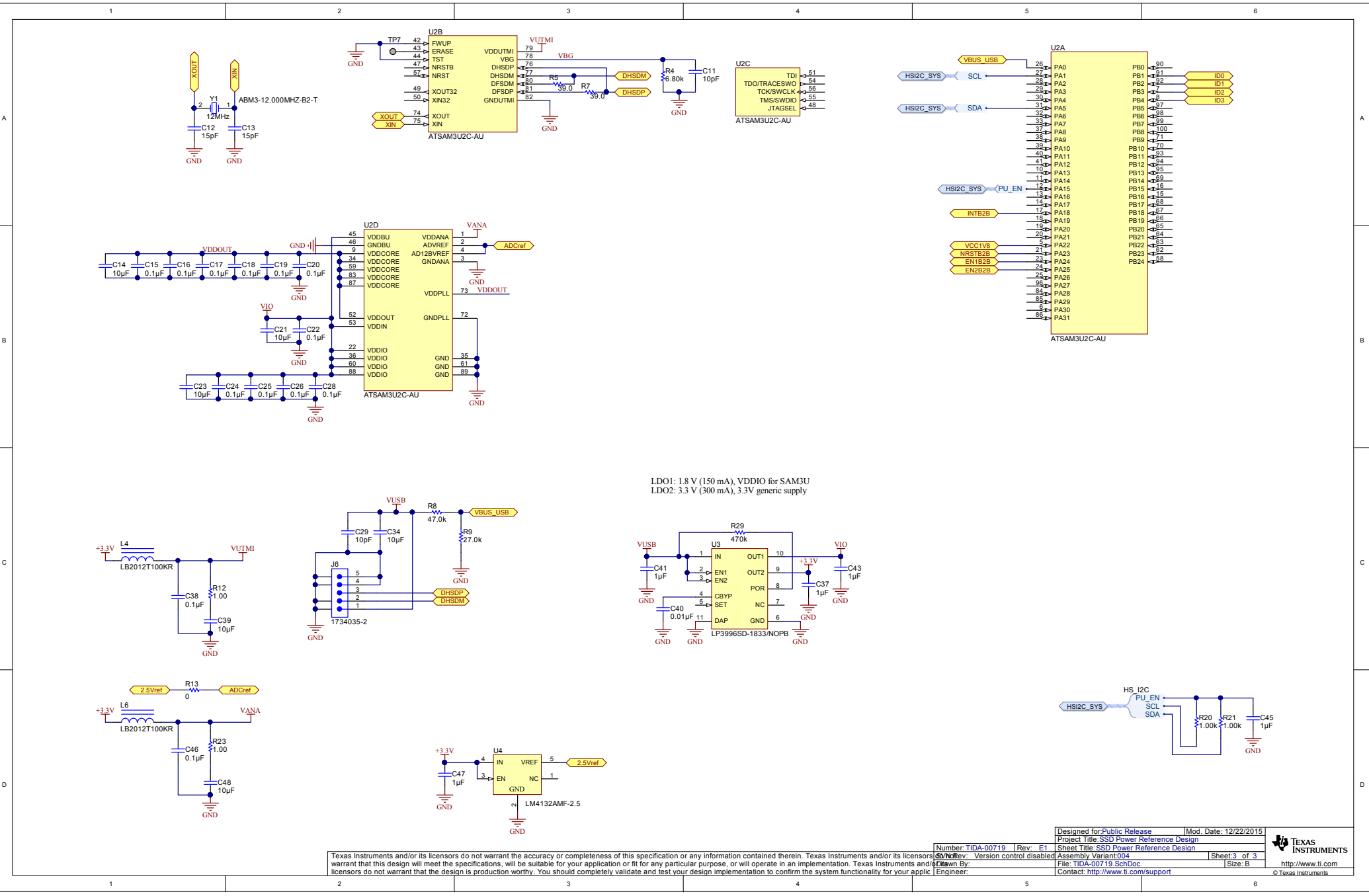
PCB
LOGO
Texas Instruments



LBL1
DNP
Size: 1.25" x 0.25"



ZZ1
Assembly Note
Place Female Shunts at J4 (both positions) and J5.



LDO1: 1.8 V (150 mA), VDDIO for SAMSU
 LDO2: 3.3 V (300 mA), 3.3V generic supply

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